NOTES:
1. CONNECT J3/14 BULB-HEAD CONNECTORS TO J3/14 ON PCB.
   CENTER CONDUCTOR GOES TO PIN 1 ON THE PCB.
2. HEAT SINK LEADS ON J304, J308 AND J310 DURING SOLDERING.
4. PARTS TO RECEIVE A CURSORY INSPECTION PRIOR TO KITTING AND INSTALLATION.
   DO NOT SOLDER PCB ASSY WITH T501 INSTALLED. INSTALL T501 AFTER ALL PARTS ARE
   INSTALLED AND THE ASSEMBLY IS CLEANED AND INSPECTED.
   TIGHTEN 4-40 HARDWARE TO 34 IN-POZ, SPOT BOND WITH F/N 11.
   TIGHTEN 6-32 HARDWARE TO 5 IN-LBS. SPOT BOND WITH F/N 11.
7. ASSEMBLY IS STATIC SENSITIVE. HANDLE IN ACCORDANCE WITH NASA-STD-8739.7.
8. MASK FOR CONFORMAL COATING, USING F/N 25, AS INDICATED. REMOVE F/N 25 AFTER CONFORMAL COATING.
9. VACUUM BAKE ALL CONNECTORS AT 800C FOR 72 HOURS PRIOR TO KITTING AND INSTALLATION.
10. CONFORMAL COATING USING F/N 10.
    - Curing at 255°C, ambient pressure for 8 hours.
    - Remove masking and masking residue prior to bake.
    - Vacuum bake at 55°C, 10⁻¹ TORR for 24 hours.
11. SPOT BOND COMPONENTS WITH F/N 12 AND F/N 29, (ARAPINE, 5753, WITH ALUMINUM POWDER)
    12. INSTALL F/N 7 AS REQUIRED FOR FLIGHT PCB ASSY TESTING. UPON COMPLETION OF TESTING,
        REMOVE TEST POINTS.
    14. MOUNT F/N 15 ON U20 USING F/N 13. SOLDER U31, (F/N 5064), AND F/N 16 TO F/N 15 AND
        TERMINATE WIRES ON U31 POINTS ON PCB. SPOT BOND U31 AND F/N 16 TO U20 USING F/N 12.
    15. USE SMALL PATTERN MOUNTING HARDWARE. INSURE CLEARANCE OF PCB TRACKS.
    16. REMOVE 0.030" FROM STANDOFFS THAT MOUNT TO THE PCB.
    17. D11-016 POLARITY IS INCORRECTLY MARKED ON THE BARE PCB. REMOVE SILKSCREEN
        DIODE SYMBOL AND INSTALL DIODES USING THE MARKING AS SHOWN IN THIS DRAWING.
    18. SPACE Q1, U201-2504 OFF F/N 1 0.03" - 0.04".
    19. INSTALL F/N 30 THRU F/N 51 AND SOLDER INTO F/N 51 AND F/N 52 ON PCB.